

Title (en)  
Polyamide resin composition

Title (de)  
Polyamid Harzzusammensetzung

Title (fr)  
Composition de résine polyamide

Publication  
**EP 0940444 B1 20040929 (EN)**

Application  
**EP 99104242 A 19990303**

Priority  
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Abstract (en)  
[origin: EP0940444A2] A polyamide resin composition comprising 100 parts by weight of a polyamide resin and 0.005 to 1.0 part by weight of at least one compound selected from the group consisting of a metal salt of a fatty acid, a diamide compound and a diester compound. The polyamide resin is obtained by solid phase-polymerizing a polyamide resin prepared by melt-polymerizing a diamine component containing 70 mol% or more of metaxylylenediamine and a dicarboxylic acid component containing 70 mol% or more of adipic acid, and preferably has a relative viscosity of 2.3 to 4.2 when measured at 25 DEG C using a solution of 1g polyamide resin in 100ml of 96% sulfuric acid. By adding at least one compound selected from the group consisting of the specific metal salt of fatty acid, the diamide compound and the diester compound to a solid phase-polymerized polyamide resin, shaped articles such as films, sheets and hollow containers made of the solid phase-polymerized polyamide are improved in the resistance to whitening during storage under a high humid condition, upon contacting with water or boiling water, or upon heating to a glass transition temperature or higher.

IPC 1-7  
**C08G 69/30**; **C08G 69/28**; **C08L 77/00**; **C08K 5/11**; **C08K 5/098**; **C08K 5/20**

IPC 8 full level  
**C08G 69/30** (2006.01); **C08G 69/48** (2006.01); **C08K 5/098** (2006.01); **C08K 5/20** (2006.01)

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Cited by  
AU2012216788B2; EP1029883A1; AU758289B2; CN107022189A; EP2532712A1; EP2025718A4; US6303741B1; WO03035732A1; US8273431B2; US8940379B2; EP2554887B1

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